

HVD144A

Silicon Epitaxial Trench Pin Diode for Antenna Switching

REJ03G0429-0100

(Previous: ADE-208-1591)

Rev.1.00 Nov 26, 2004

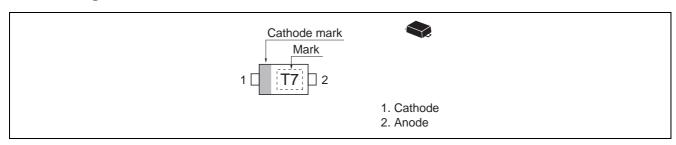
Features

- Adopting the trench structure improves low capacitance. (C = 0.43 pF max)
- Low forward resistance. (rf = $1.80 \Omega \text{ max}$)
- Low operation current.
- Super small Flat Lead Package (SFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVD144A	T7	SFP

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Reverse voltage	V _R	30	V
Forward current	I _F	100	mA
Power dissipation	Pd	150	mW
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Electrical Characteristics

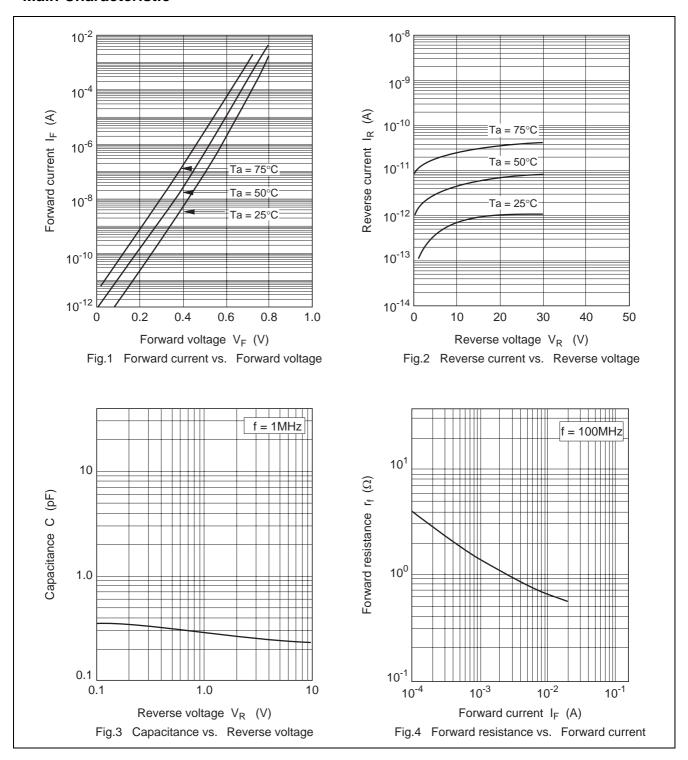
 $(Ta = 25^{\circ}C)$

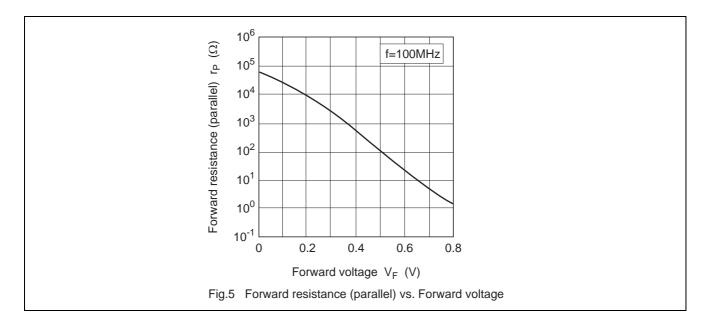
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _R	_	_	100	nA	V _R = 30 V
Forward voltage	V _F	_	_	0.90	V	$I_F = 2 \text{ mA}$
Capacitance	С	_	_	0.43	pF	V _R = 1 V, f = 1 MHz
Forward resistance	r _f	_	_	1.80	Ω	I _F = 2 mA, f = 100 MHz
ESD-Capability *1	_	100	_	_	V	$C = 200 \text{ pF}, R = 0 \Omega$, Both forward and reverse direction 1 pulse.

Notes: 1. Failure criterion ; $I_R > 100$ nA at $V_R = 30$ V

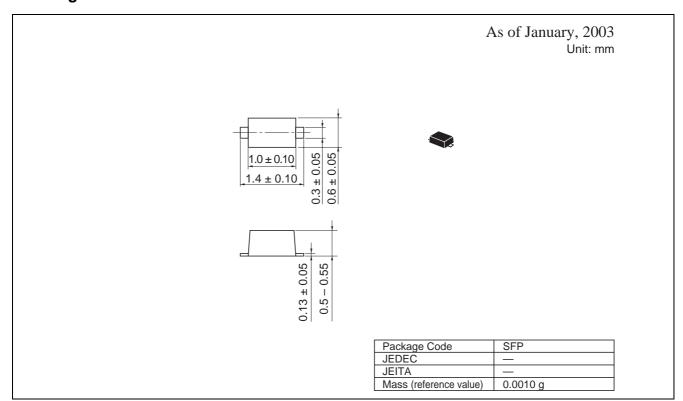
2. Please do not use the soldering iron due to avoid high stress to the SFP package.

Main Characteristic





Package Dimensions



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